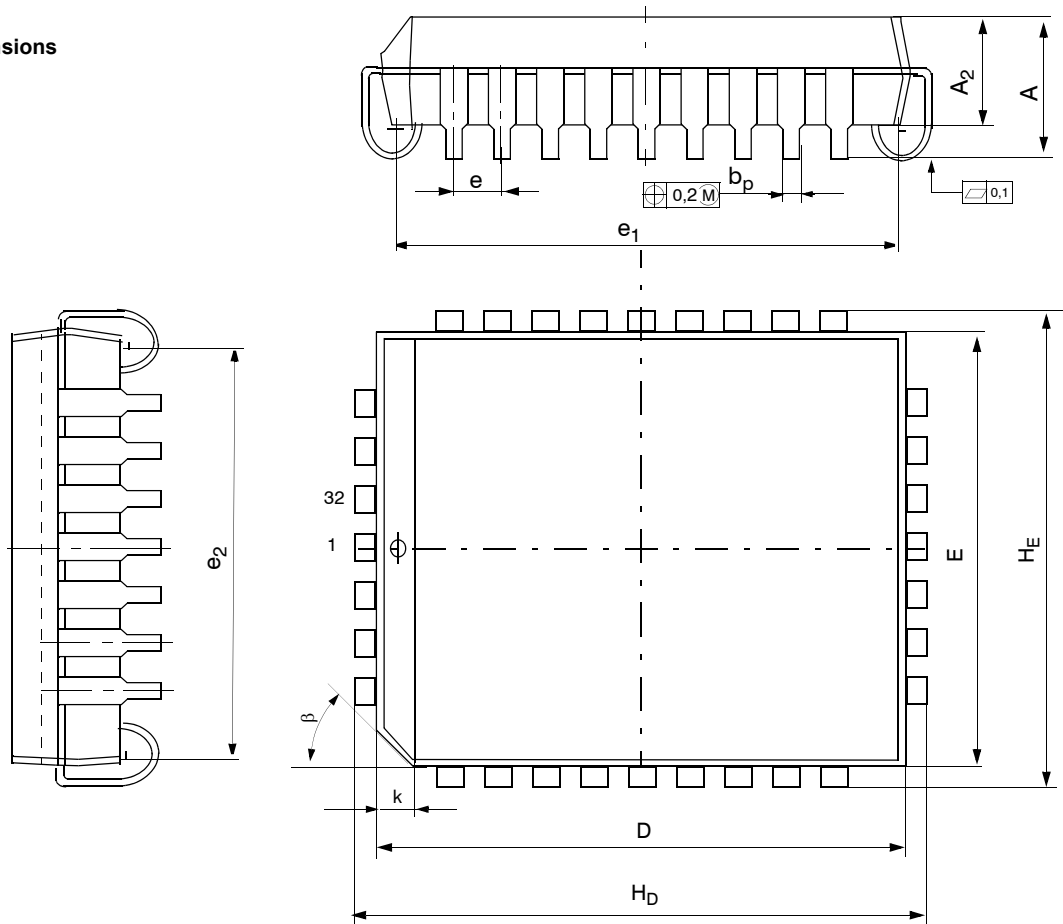


	<b>Package PLCC32</b>	<b>MDS 772</b>
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Dimensions in millimetres

Based on JEDEC MS-016 variant AE

**1 Dimensions**

Dimensions of Sub-Group B1	
$A_{max}$	3.56
$b_{Pmin}$	0.33
$b_{Pmax}$	0.53
$e_{nom}$	1.27
$H_{Dmin}$	14.85
$H_{Dmax}$	15.12
$H_{Emin}$	12.31
$H_{Emax}$	12.58

- 2 Weight**  $\leq 1.2$  g
- 3 Package Body Material** Low Stress epoxy
- 4 Lead Material** Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** J-bends
- 7**

Dimensions of Sub-Group C1	
$A_{min}$	3.17
$A_{2min}$	2.69
$A_{2max}$	2.85
$D_{min}^*$	13.94
$D_{max}^*$	14.05
$E_{min}^*$	11.40
$E_{max}^*$	11.51
$k_{min}$	1.00
$\beta$	45°
$e_{1min}$	12.44
$e_{1max}$	13.48
$e_{2min}$	9.90
$e_{2max}$	10.94

\*without mold-flash

Zentrum Mikroelektronik Dresden AG		
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